

In the Specification

Please add the following paragraphs to the specification on page 2, line 20:

Another object of the present invention is to provide a bead curing finger mold further characterized by the upper fingers and the lower fingers having sloped edges for guiding and compressing the bead bundle in a central position upon closing of the mold.

Another object of the present invention is to provide a bead curing finger mold further characterized by the upper fingers and the lower fingers having molding surfaces providing a circular molding member surface of the mold with a precise predetermined diameter of the bead bundle upon closing of the mold.

Another object of the present invention is to provide a bead curing finger mold wherein the bead bundle is a tire bead having a plurality of wires wrapped in a the bead bundle and coated with an elastomeric material further characterized by means for heating the mold for vulcanizing the elastomeric material.

Another object of the present invention is to provide a bead curing finger mold further characterized by the upper fingers and the lower fingers having extensions extending beyond the molding surfaces for guiding the bead bundle and providing recesses for receiving the extensions in the closed condition of the mold.

Another object of the present invention is to provide a bead curing finger mold further characterized by the lower finger mold half being raised to close the mold and the upper finger mold half has spaced apart spring loaded ejector fingers for retracting upon closing of the mold and for extension upon opening of the mold to transfer the bead bundle to the lower finger mold half.

Another object of the present invention is to provide a bead curing finger mold further characterized by the lower finger mold half having circumferentially spaced apart ejectors and bead holders extending upwardly through the lower finger mold half for holding the bead bundle in the lower position of the lower finger mold half prior to closing of the mold and ejecting the bead bundle upon lowering of the upper mold half after vulcanization of the bead bundle.